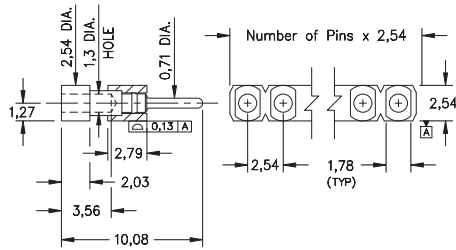


INTERCONNECTS

SERIES 800, 801, 830 • 2,54 GRID (0,76 DIA. PINS), SURFACE MOUNT HEADERS AND SOCKETS • SINGLE ROW STRIPS

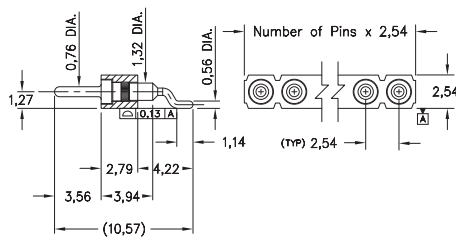
Mates with Series 801...002 Surface Mount Z-Bend Socket (See Fig. 3)



Coplanarity 0,13. For pin counts >10 positions, consult Technical Support.

FIG. 1

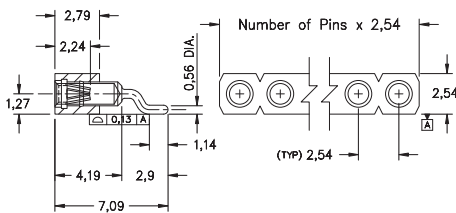
Mates with Series 801...002 Surface Mount Z-Bend Socket (See Fig. 3)



Coplanarity 0,13. For pin counts >10 positions, consult Technical Support.

FIG. 2

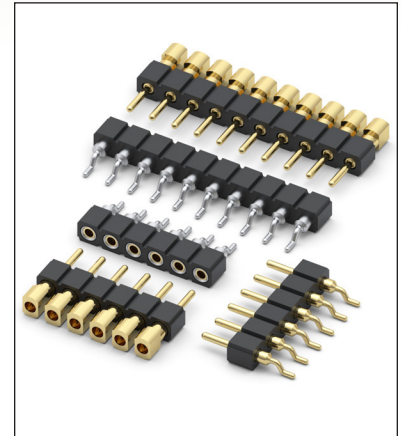
Mates with Series 800...002 and 830...028 Surface Mount Header (See Fig. 1 & 2)



Coplanarity 0,13. For pin counts >10 positions, consult Technical Support.

FIG. 3

- Series 800 horizontal surface mount headers are available with 0,71 dia. pluggable pins (MM #1502). Series 830 horizontal surface mount z-bend headers use MM #3028 pins. See page 224 for details
- Series 801 horizontal surface mount Z-Bend sockets uses MM #1303 receptacles that accept pin diameters from 0,64 - 0,94 and 0,64 square leads. See pages 180 for details
- Insulators are high temperature thermoplastic, suitable for all soldering operations
- Ideal for daisy chaining parallel boards



ORDERING INFORMATION



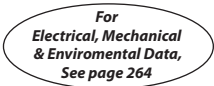





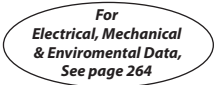





FIG. 1	Series 800...002	0,71 Dia. Surface Mount Header		
		800-10-0	-40-002000	02-10
FIG. 2	Series 830...028	0,76 Dia. Surface Mount Z-Bend Header		
		830-XX-0	-40-028000	02-10
  				
SPECIFY PLATING CODE XX=		10 	40 	
Pin Plating 		0,25µm Au	5,08µm Sn	

FIG. 3	Series 801...002	0,71 Dia. Surface Mount Z-Bend Socket					
		801-XX-0	-40-002000	02-10			
  							
SPECIFY PLATING CODE XX=		91	93	99	41 	43 	44 
Sleeve (Pin) 		5,08µm Sn/Pb	5,08µm Sn/Pb	5,08µm Sn/Pb	5,08µm Sn	5,08µm Sn	5,08µm Sn
Contact (Clip) 		0,25µm Au	0,76µm Au	2,54µm Sn/Pb	0,25µm Au	0,76µm Au	2,54µm Sn

